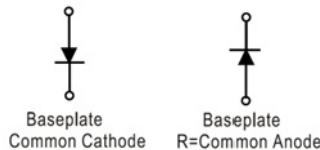


Low V_F Silicon Power Schottky Diode

V_{RRM} = 30 V
I_{F(AV)} = 200 A

Features

- High Surge Capability
- Type 30 V V_{RRM}
- Not ESD Sensitive

D-67 Package


Maximum ratings, at T_j = 25 °C, unless otherwise specified ("R" devices have leads reversed)

Parameter	Symbol	Conditions	MBRH20030(R)L	Unit
Maximum recurrent peak reverse voltage	V _{RRM}		30	V
Maximum RMS voltage	V _{RMS}		21	V
Maximum DC blocking voltage	V _{DC}		30	V
Operating temperature	T _j		-55 to 150	°C
Storage temperature	T _{stg}		-55 to 150	°C

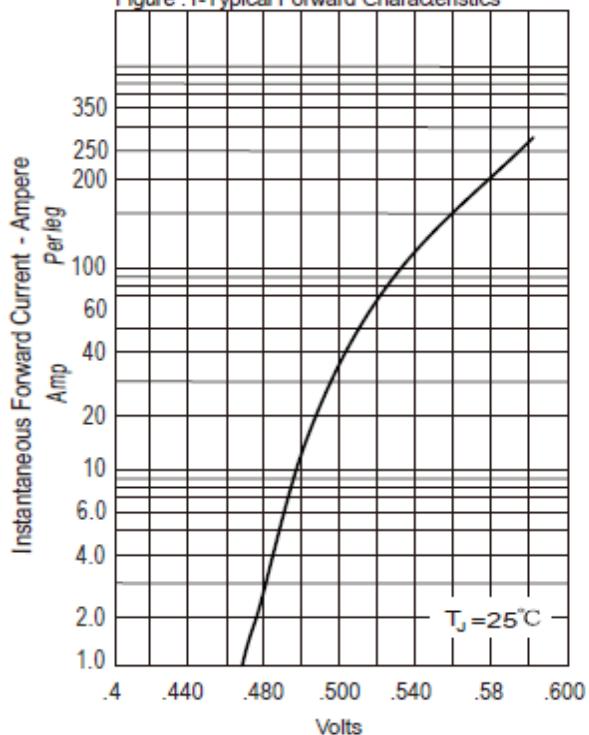
Electrical characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	MBRH20030(R)L	Unit
Average forward current	I _{F(AV)}	T _C = 100 °C	200	A
Peak forward surge current	I _{FSM}	t _p = 8.3 ms, half sine	3000	A
Maximum instantaneous forward voltage	V _F	I _{FM} = 200 A, T _j = 25 °C	0.58	V
Maximum instantaneous reverse current at rated DC blocking voltage	I _R	T _j = 25 °C T _j = 100 °C	3 150	mA

Thermal characteristics

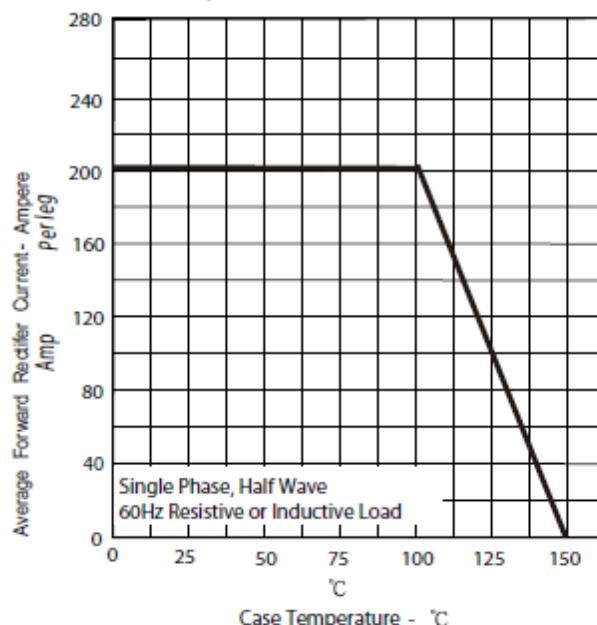
Maximum thermal resistance, junction - case	R _{θJC}	0.35	°C/W
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Figure .1-Typical Forward Characteristics



Instantaneous Forward Voltage - Volts

Figure .2-Forward Derating Curve



Case Temperature - °C

Figure .3-Peak Forward Surge Current

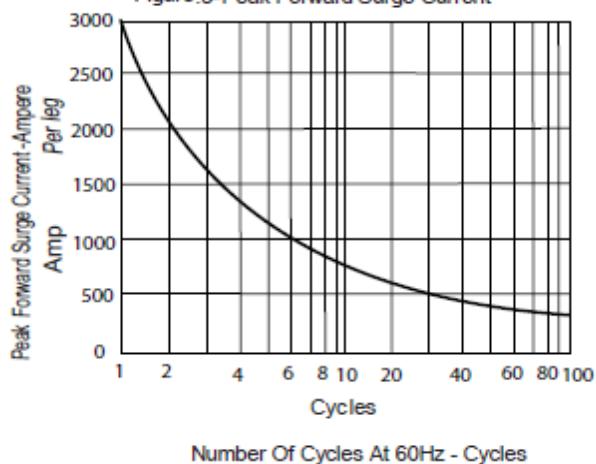
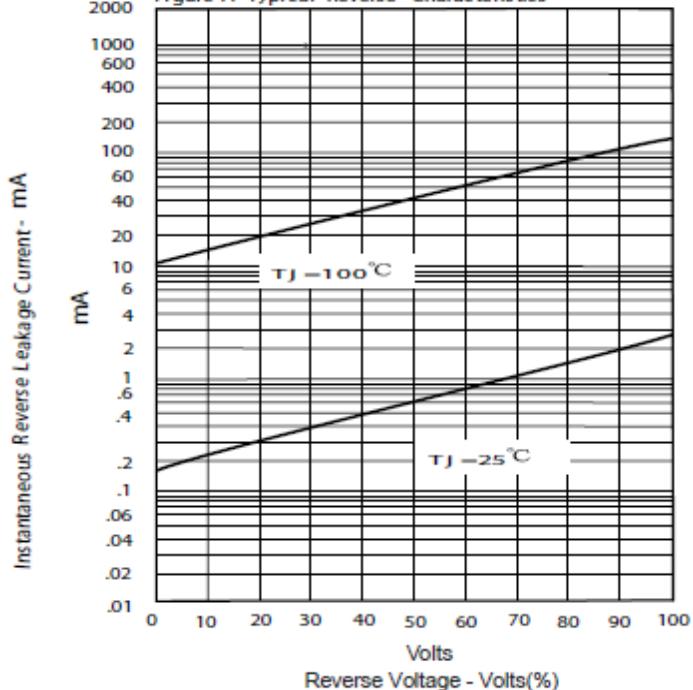
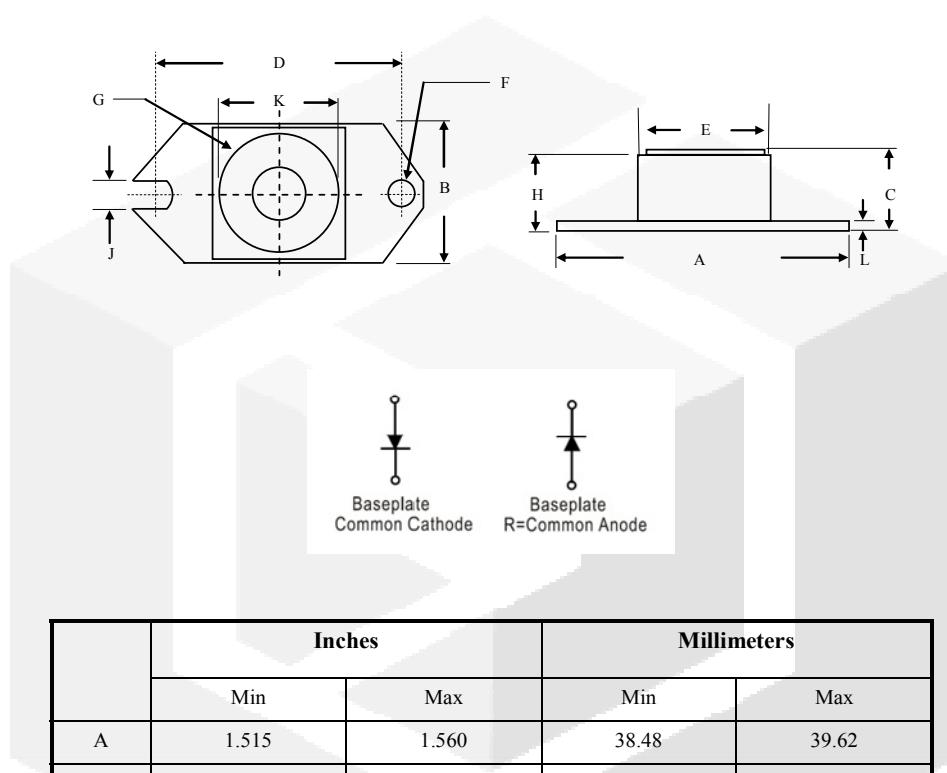


Figure .4-Typical Reverse Characteristics



Package dimensions and terminal configuration

Product is marked with part number and terminal configuration.



	Inches		Millimeters	
	Min	Max	Min	Max
A	1.515	1.560	38.48	39.62
B	0.725	0.775	18.42	19.69
C	0.595	0.625	15.11	15.88
D	1.182	1.192	30.02	30.28
E	0.736	0.744	18.70	18.90
F	0.152	0.160	3.86	4.061
G	1/4-20 UNC			
H	0.540	0.580	13.72	14.73
J	0.156	0.160	3.96	4.06
K	0.480	0.492	12.20	12.50
L	0.120	0.130	3.05	3.30